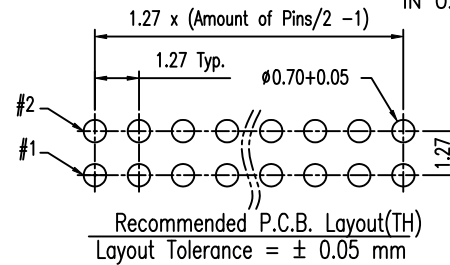


NOTE:

1. MATERIAL,
HOUSING: HIGH TEMP THERMAL PLASTIC, UL94-V0
TERMINAL: COPPER ALLOY
2. FINISH:
TERMINAL: GOLD AT CONTACT,
G/F OVER 1UM(40U")MIN Ni OVER ALL
3. SPEC.:
PRODUCT SPEC: GS-12-629
PACKING SPEC: GS-14-1517
4. THE HSG. WILL WITHSTAND EXPOSURE TO 260C
PEAK TEMP. FOR 10 SEC. IN A WAVE SOLDER APPLICATION.
5. MATING SIDE LENGTH: 2.5MM MIN.
6. PRODUCT NUMBERING:
200218 24 - XXX XX X X LF

LEAD FREE
PLATING:
1: G/F ALL OVER
4: 0.25UM(10U")GOLD AT CONTACT
8: 0.76UM(30U")GOLD AT CONTACT
PACKING
T: TUBE
PIN COUNT
04, 06, 08, ..., 98, A0
(EVERY EVEN PIN)
STACK HEIGHT "K"
EXAMPLE: 045=4.5MM
IN 0.5MM INCREMENT



mat'l. code		surface <input checked="" type="checkbox"/> tolerance		projection	product family 585
ltr	ecn no	dr	date	tolerances unless otherwise specified	
A	T10-0182	S.LIN	10'-10-07	MM	title 1.27X1.27MM BTB STACK HD VT, TH
				scale N/A	dwg no 20021824
					sheet 1 of 1 size A4
					type CUSTOMER Drawing
sheet index	revision	A	sheet	1	

Mouser Electronics

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